



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

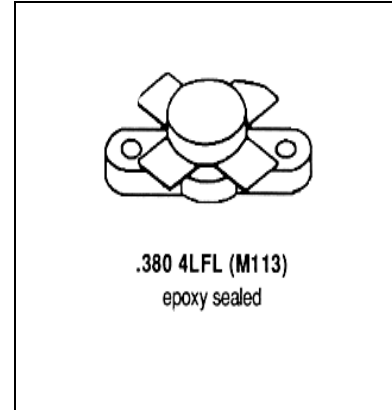
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

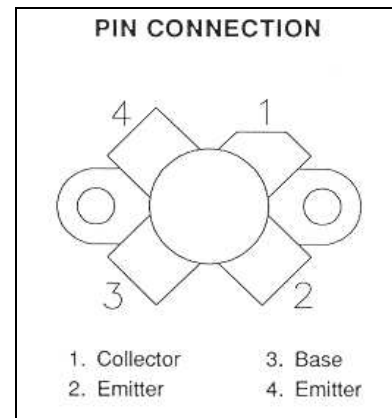


MS1226
**RF & MICROWAVE TRANSISTORS
HF SSB APPLICATIONS**
Features

30 MHz
 28 VOLTS
 IMD = -28 dB
 $P_{OUT} = 30$ WATTS
 $G_P = 18$ dB MINIMUM
 COMMON EMITTER CONFIGURATION


DESCRIPTION:

The MS1226 is a 28V epitaxial silicon NPN planar transistor designed primarily for SSB communications. This device utilizes emitter ballasting for improved ruggedness and reliability.


ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V_{CBO}	Collector-base Voltage	65	V
V_{CEO}	Collector-emitter Voltage	36	V
V_{EBO}	Emitter-Base Voltage	4.0	V
I_C	Device Current	4.5	A
P_{DISS}	Power Dissipation	80	W
T_J	Junction Temperature	+200	C
T_{STG}	Storage Temperature	-65 to +150	C

Thermal Data

$R_{TH(J-C)}$	Junction-case Thermal Resistance	2.2	C/W
---------------	----------------------------------	-----	-----

ELECTRICAL SPECIFICATIONS (T_{case} = 25°C)
STATIC

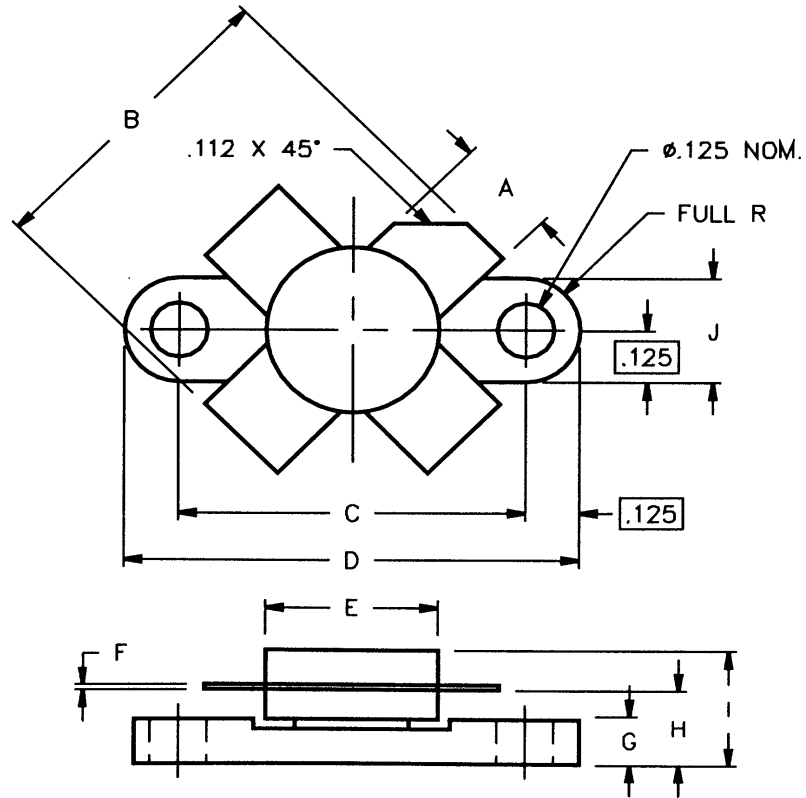
Symbol	Test Conditions		Value			Unit
			Min.	Typ.	Max.	
BV _{cbo}	I _C = 200 mA	I _E = 0 mA	65	---	---	V
BV _{ces}	I _C = 200 mA	V _{BE} = 0 V	65	---	---	V
BV _{ceo}	I _C = 200 mA	I _B = 0 mA	35	---	---	V
BV _{ebo}	I _E = 10 mA	I _C = 0 mA	4.0	---	---	V
I _{cbo}	V _{CB} = 30 V	I _E = 0 mA	---	---	1.0	mA
H _{FE}	V _{CE} = 5 V	I _C = 500 mA	10	---	200	---

DYNAMIC

Symbol	Test Conditions			Value			Unit
				Min.	Typ.	Max.	
P _{OUT}	f = 30 MHz	P _{IN} = 0.48W	V _{CE} = 28V	30	---	---	W
G _P	f = 30 MHz	P _{IN} = 0.48W	V _{CE} = 28V	18	---	---	dB
IMD	f = 30 MHz	P _{IN} = 0.48W	V _{CE} = 28V	---	----	-28	dB _C
Cob	f = 1 MHz	V _{CB} = 30V		---	---	65	pf
Conditions	V _{CE} = 28 V	I _{CQ} = 25 mA					

MS1226

PACKAGE MECHANICAL DATA



	MINIMUM INCHES/MM	MAXIMUM INCHES/MM		MINIMUM INCHES/MM	MAXIMUM INCHES/MM
A	.220/5,59	.230/5,84	I		.260/7,11
B	.785/19,94		J	.240/6,10	.255/6,48
C	.720/18,29	.730/18,54			
D	.970/24,64	.980/24,89			
E		.385/9,78			
F	.004/0,10	.006/0,15			
G	.085/2,16	.105/2,67			
H	.160/4,06	.180/4,57			